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United States Patent [19]

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Dressen

[45] Date of Patent: **** Mar. 8, 1994**

[54] **DISC PACKAGE FOR SEMICONDUCTOR WAFERS**

4,588,086	5/1986	Coe	206/444
4,793,488	12/1988	Mortensen	206/454
4,966,284	10/1990	Gregerson et al.	206/334

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[73] Assignee: **Empak, Inc., Chanhassen, Minn.**

[**] Term: **14 Years**

[21] Appl. No.: **829,171**

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[52] U.S. Cl. **D9/424; 206/334; 206/508**

[58] Field of Search **211/40; 206/334, 328, 206/444, 454, 455, 508; D9/337, 424, 425; D14/299**

[56] **References Cited**

U.S. PATENT DOCUMENTS

D. 260,237 8/1981 Fuzere 206/454 X

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Assistant Examiner—Richelle Shelton
Attorney, Agent, or Firm—Haugen and Nikolai

[57] **CLAIM**

The ornamental design for the disc package for semiconductor wafers, as shown and described.

DESCRIPTION

FIG. 1 is a top front perspective view of a disc package for semiconductor wafers;
FIG. 2 is a front elevational view thereof, the undisclosed rear portion is a mirror image of the front;
FIG. 3 is a top plan view thereof;
FIG. 4 is a bottom plan view thereof; and,
FIG. 5 is a side elevation view thereof, the opposite side is a mirror image of the side shown.

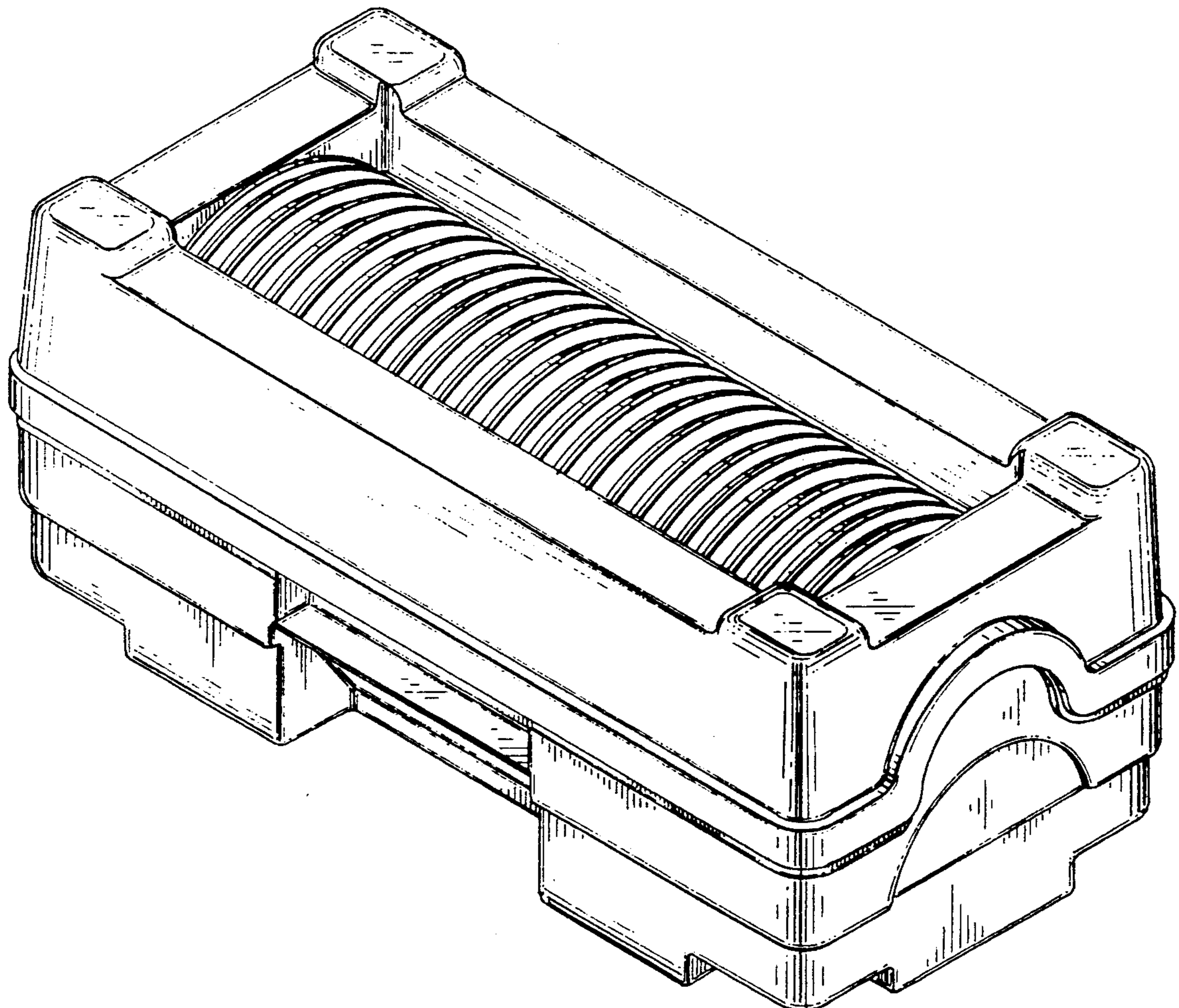


Fig.-1

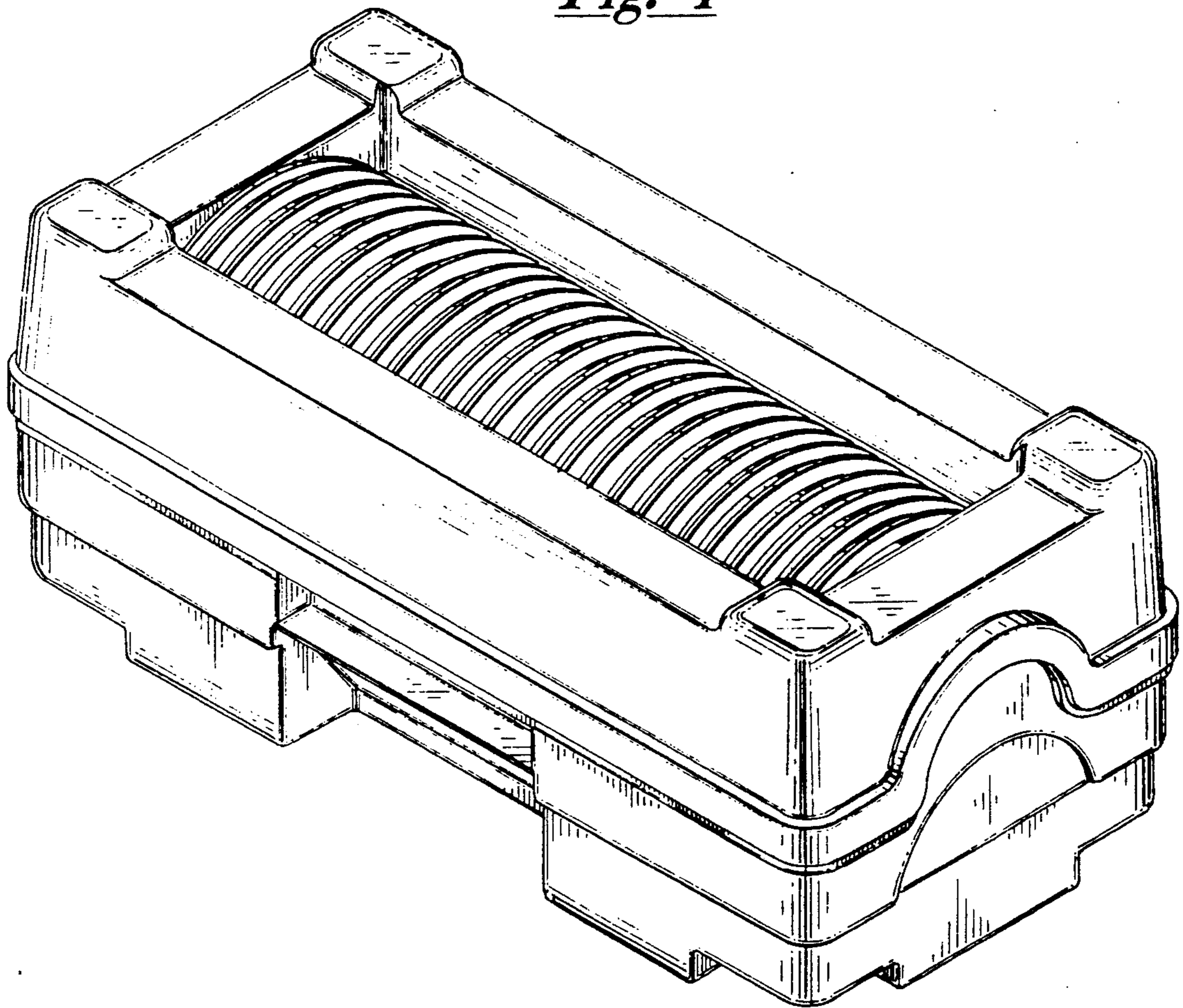


Fig.-2

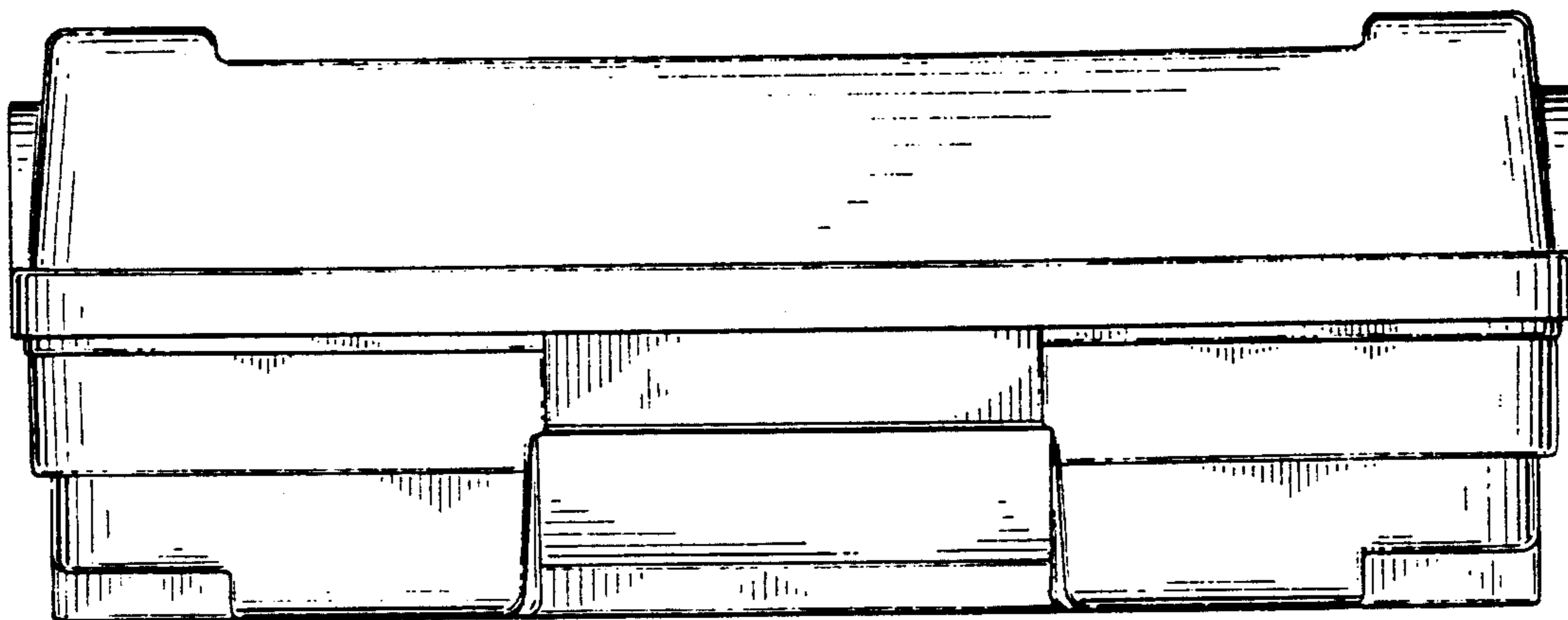


Fig.-3

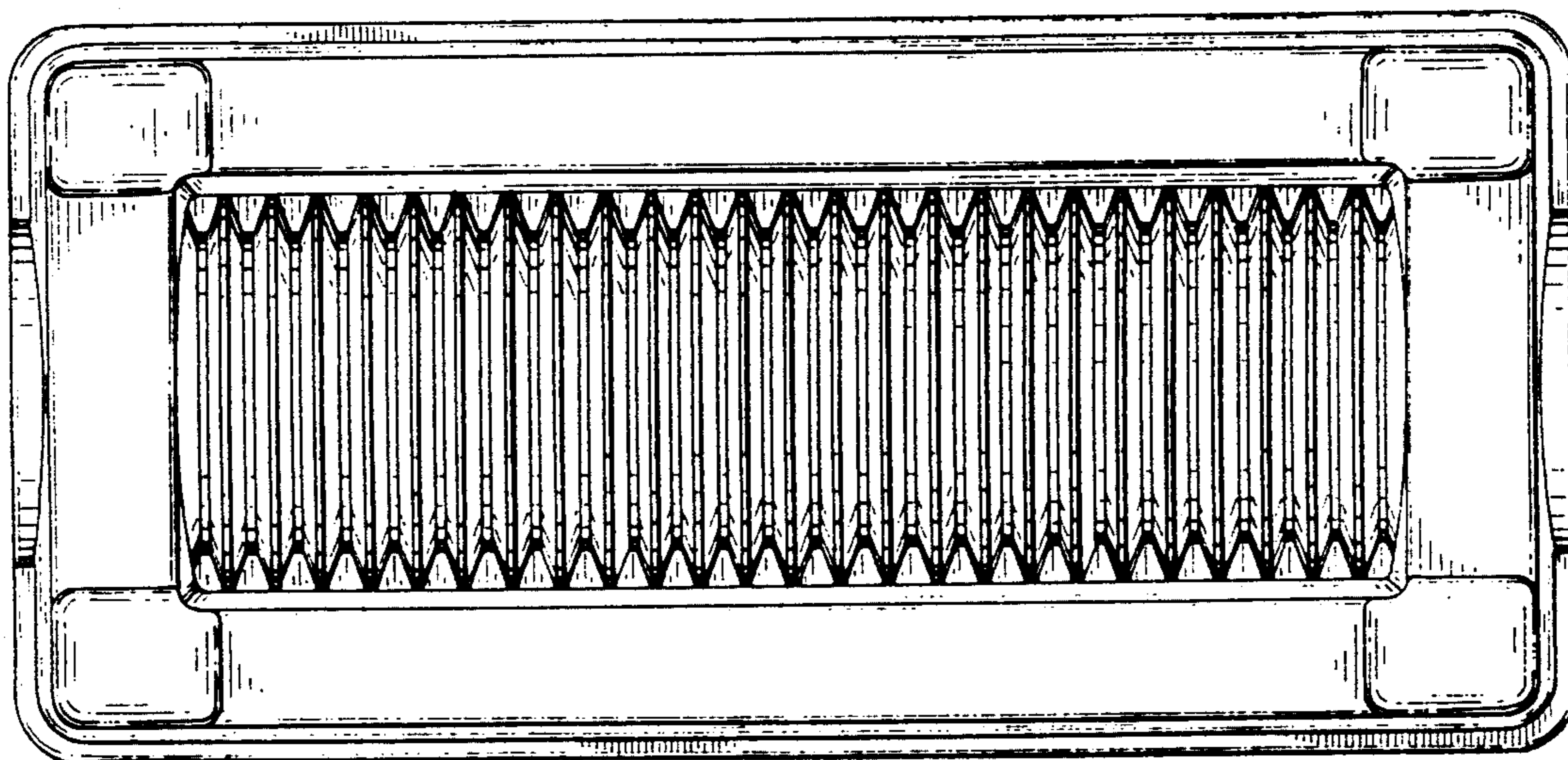


Fig. -4

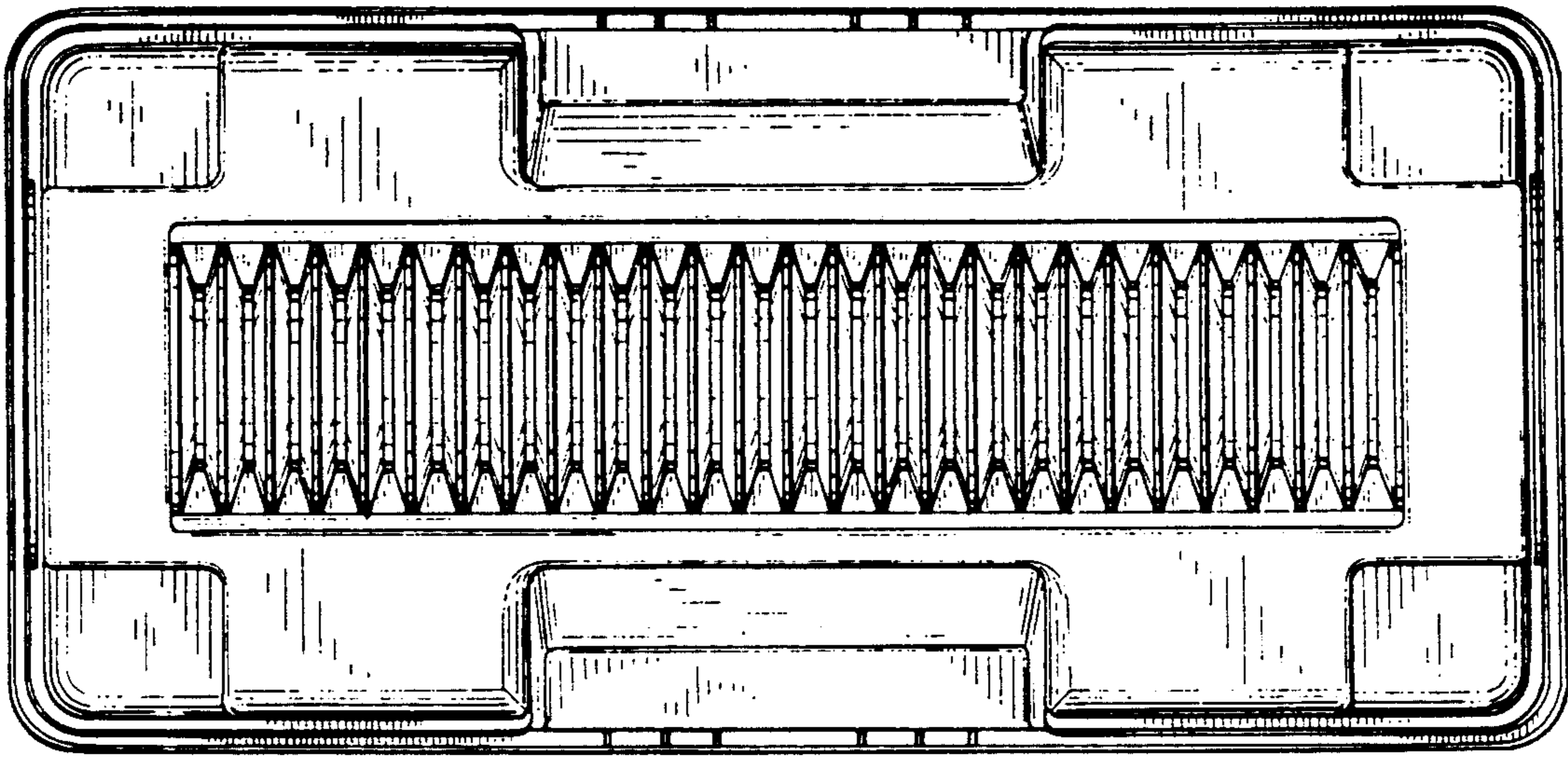


Fig. -5

